

# Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit		
Collector-Base Voltage		V <sub>CBO</sub>	-20			
Collector-Emitter Voltage		V <sub>CEO</sub>	-12	V		
Emitter-Base Voltage		V <sub>EBO</sub>	-7			
Peak Pulse Current		I <sub>CM</sub>	-12			
Continuous Collector Current	(Note 4)	1-	-4			
	(Note 5)	Ic	-4.5	^		
Base Current		I <sub>B</sub>	-1			

# Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 4)		1.5 12	W mW/°C	
Linear Derating Factor	(Note 5)	PD	2.45 19.6		
Thermal Resistance, Junction to Ambient	(Note 4)	D	83		
Thermal Resistance, Junction to Ambient	(Note 5)	R <sub>θJA</sub>	51	°C/W	
Thermal Resistance, Junction to Lead	(Note 6)	$R_{ hetaJL}$	16.8		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

Notes:

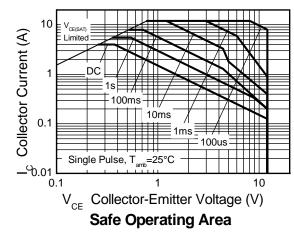
 <sup>4.</sup> For a device surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The entire exposed collector pad is attached to the heatsink.
5. Same as note (4), except the device is measured at t ≤ 5 sec.

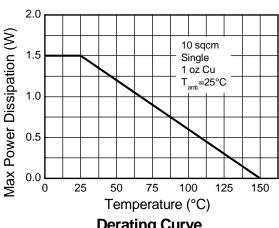
<sup>6.</sup> For a single device, thermal resistance from junction to solder-point (at the end of the drain lead).





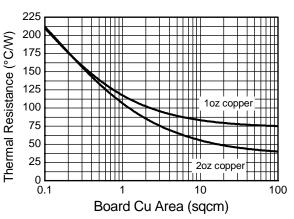
#### **Thermal Characteristics**





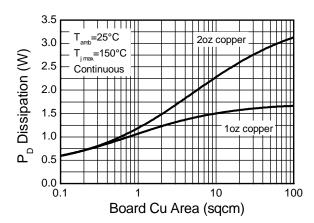
#### 10 sqcm Thermal Resistance (°C/W) Single 1 oz Cu D = 0.5Single Pulse 10m 100m 10 1m 100 1k Pulse Width (s)

**Derating Curve** 



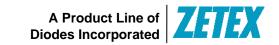
#### **Transient Thermal Impedance**

Thermal Resistance v Board Area



Power Dissipation v Board Area





### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

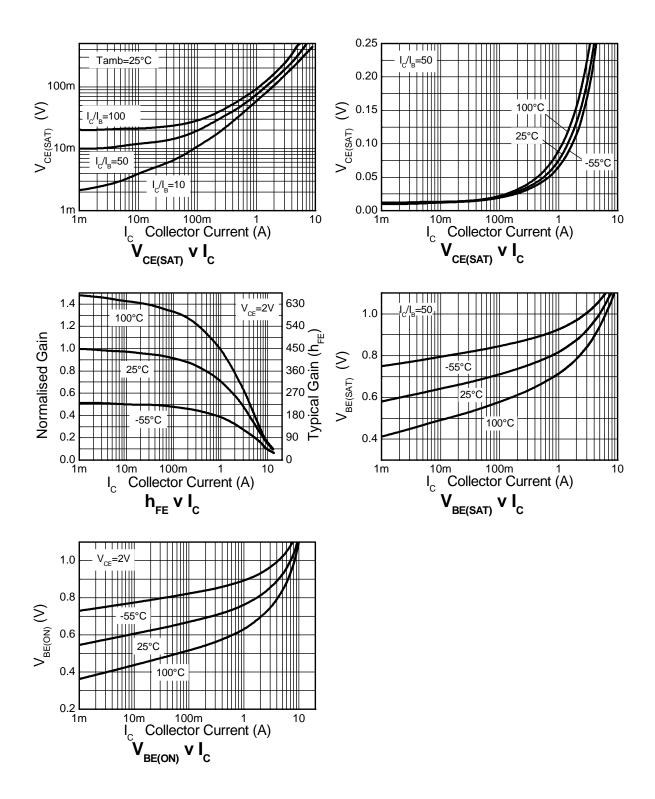
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_CBO$	-20	-35	-	V	I <sub>C</sub> = -100 μA
Collector-Emitter Breakdown Voltage (Note 7)	BV <sub>CEO</sub>	-12	-25	-	V	I <sub>C</sub> = -10 mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.5	-	V	I <sub>E</sub> = -100 μA
Collector Cutoff Current	I <sub>CBO</sub>	-	-	-100	nA	V <sub>CB</sub> = -16V
Emitter Cutoff Current	I <sub>EBO</sub>	-	-	-100	. nA	V <sub>EB</sub> = -6V
Collector Emitter Cutoff Current	I <sub>CES</sub>	-	-	-100	nA	V <sub>CES</sub> = -10V
Static Forward Current Transfer Ratio (Note 7)	h <sub>FE</sub>	300 300 180 60 45	475 450 275 100 70	- - - -	-	$I_{C}$ = -10mA, $V_{CE}$ = -2V $I_{C}$ = -100mA, $V_{CE}$ = -2V $I_{C}$ = -2.5A, $V_{CE}$ = -2V $I_{C}$ = -8A, $V_{CE}$ = -2V $I_{C}$ = -10A, $V_{CE}$ = -2V
Collector-Emitter Saturation Voltage (Note 7)	V <sub>CE(sat)</sub>		-10 -100 -100 -195 -240	-17 -140 -150 -300 -310	mV	$I_C$ =- 0.1A, $I_B$ = -10mA $I_C$ = -1A, $I_B$ = -10mA $I_C$ = -1.5A, $I_B$ = -50mA $I_C$ = -3A, $I_B$ = -50mA $I_C$ = -4A, $I_B$ = -150mA
Base-Emitter Turn-On Voltage (Note 7)	V <sub>BE(on)</sub>	-	-0.87	-0.96	V	I <sub>C</sub> = -4A, V <sub>CE</sub> = -2V
Base-Emitter Saturation Voltage (Note 7)	V <sub>BE(sat)</sub>	-	-0.97	-1.07	V	$I_C = -4A$ , $I_B = -150mA$
Output Capacitance	C <sub>obo</sub>	-	21	30	pF	V <sub>CB</sub> = -10V. f = 1MHz
Transition Frequency	f <sub>T</sub>	100	110	-	MHz	$V_{CE} = -10V, I_{C} = -50mA,$ f = 100MHz
Turn-On Time	t <sub>on</sub>	-	70	-	ns	$V_{CC} = -6V, I_C = -2A$
Turn-Off Time	t <sub>off</sub>	-	130	-	ns	$I_{B1} = I_{B2} = -50 \text{mA}$

Notes: 7. Measured under pulsed conditions. Pulse width  $\leq$  300  $\mu$ s. Duty cycle  $\leq$  2%.





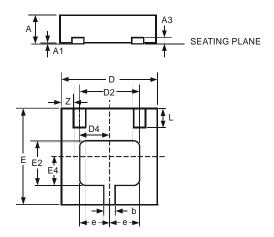
### **Typical Electrical Characteristics**





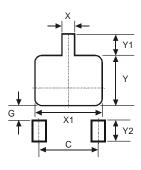


# Package Outline Dimensions



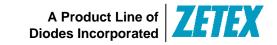
DFN2020B-3					
Dim	Min	Max	Тур		
Α	0.57	0.63	0.60		
A1	0	0.05	0.02		
A3	_	_	0.152		
b	0.20	0.30	0.25		
D	1.95	2.075	2.00		
D2	1.22	1.42	1.32		
D4	0.56	0.76	0.66		
е	_	_	0.65		
Е	1.95	2.075	2.00		
E2	0.79	0.99	0.89		
E4	0.48	0.68	0.58		
L	0.25	0.35	0.30		
Z	_		0.225		
All Dimensions in mm					

# **Suggested Pad Layout**



Dimensions	Value (in mm)
С	1.30
G	0.24
Х	0.35
X1	1.52
Υ	1.09
Y1	0.47
Y2	0.50





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